

This document can handle board shapes up to 7.9in x 10in, although our panel vendors top out at 7in x 10in.

To re-size the board shape, do the following:

Select lines on M1 Board Outline and delete (easy in single layer mode...shift+s)

Draw a rectangle using lines (example will be for a 4 x 6 board)

Enter Place Line mode (keyboard pl)

keyboard jo to jump to origin, hit enter

keyboard jl to jump to location, set x to 6000, hit enter twice

keyboard jl to jump to location, set x to 6000 and y to 4000, hit enter twice

keyboard jl to jump to location, set x to 0 and y to 4000, hit enter twice

keyboard jo to jump to origin, hit enter

Hit ESC twice to exit place line mode

Select lines on M1 Board Outline

Menu DesignBoard ShapeDefine from Selected Objects (keyboard dsd)

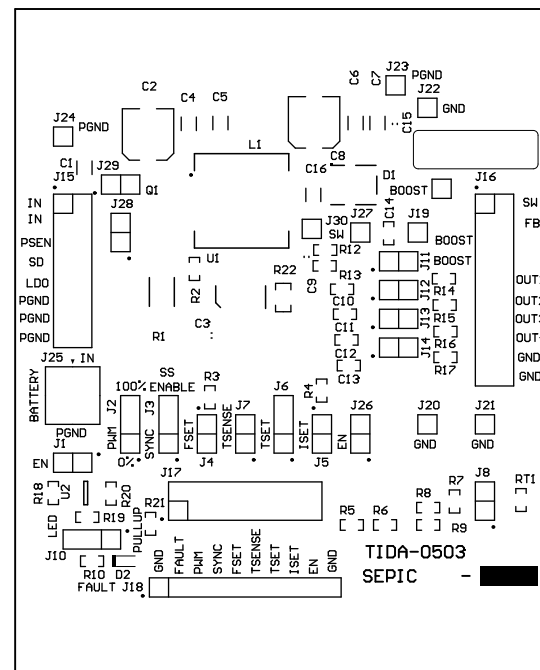
To define a Keep-Out that mirrors the board outline:

Menu DesignBoard ShapeCreate Primitives From Board Shape (keyboard dsp)

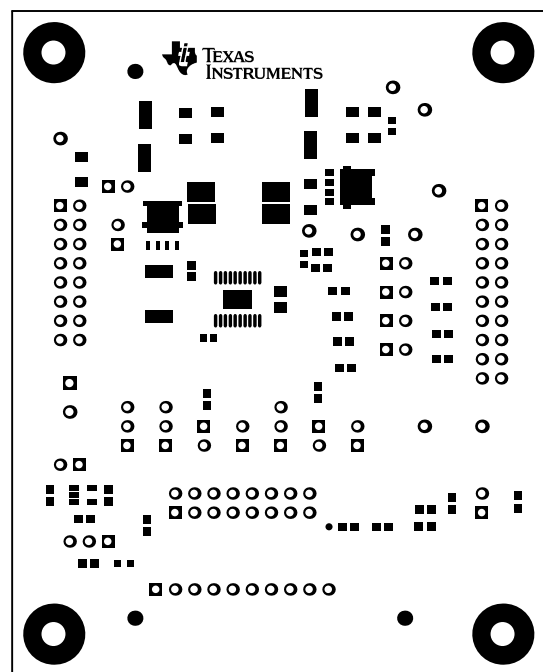
Set the Keep-Out Layer as the layer, set width as preferred

Ensure Route Tool Outline is selected, hit enter

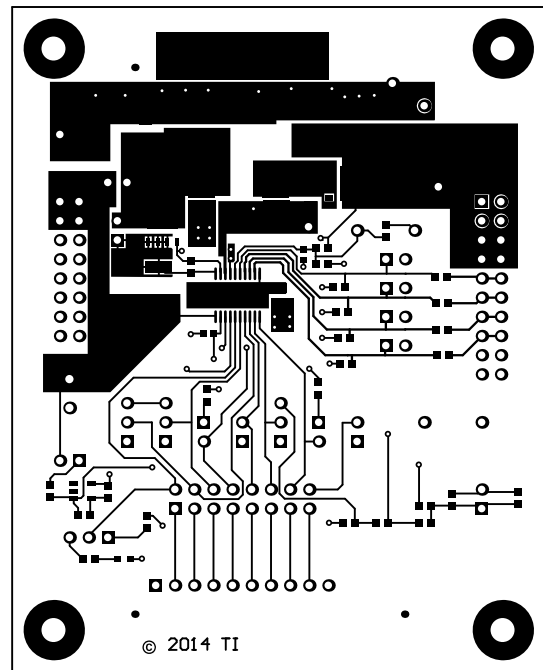
If you re-size the board, don't forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape



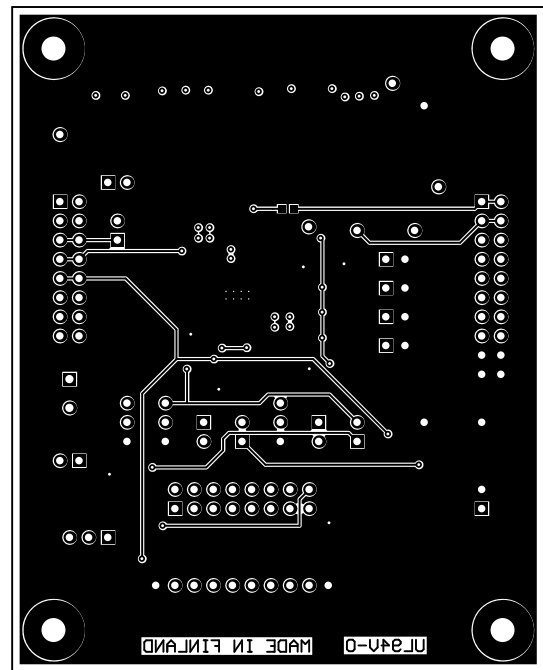
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 24.9.2015 13:30:46	TEXAS INSTRUMENTS	



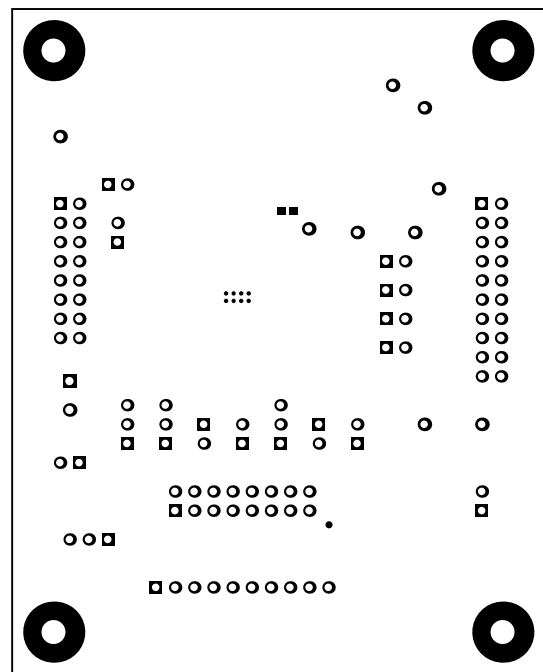
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 24.9.2015 13:30:47	TEXAS INSTRUMENTS	



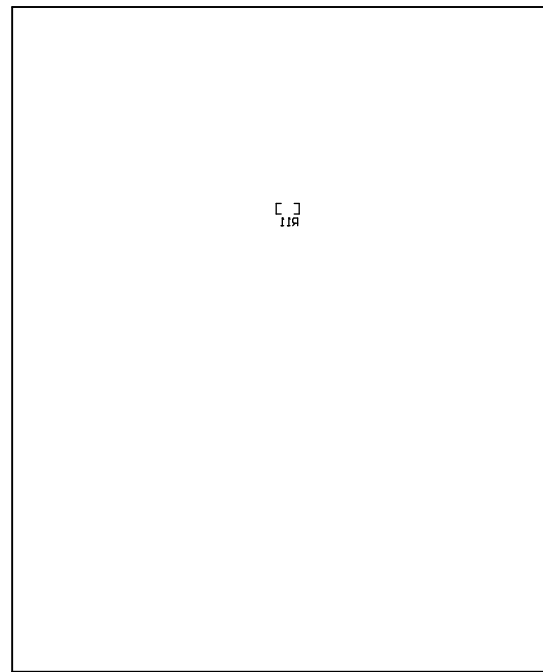
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 24.9.2015 13:30:48	TEXAS INSTRUMENTS	



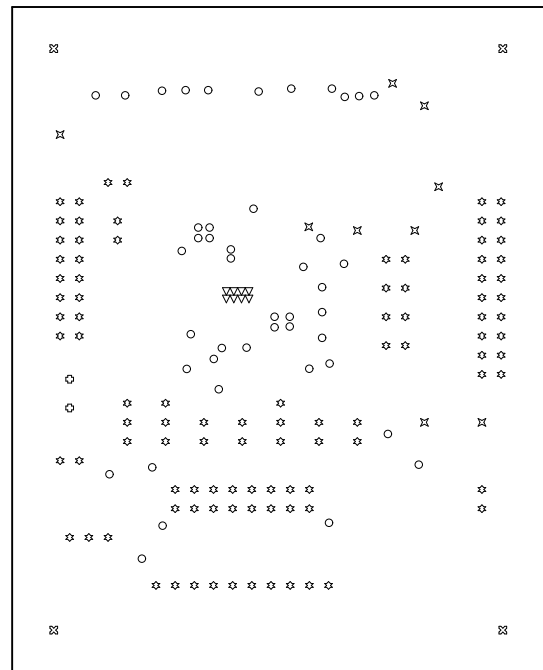
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 24.9.2015 13:30:50	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 24.9.2015 13:30:51	TEXAS INSTRUMENTS	



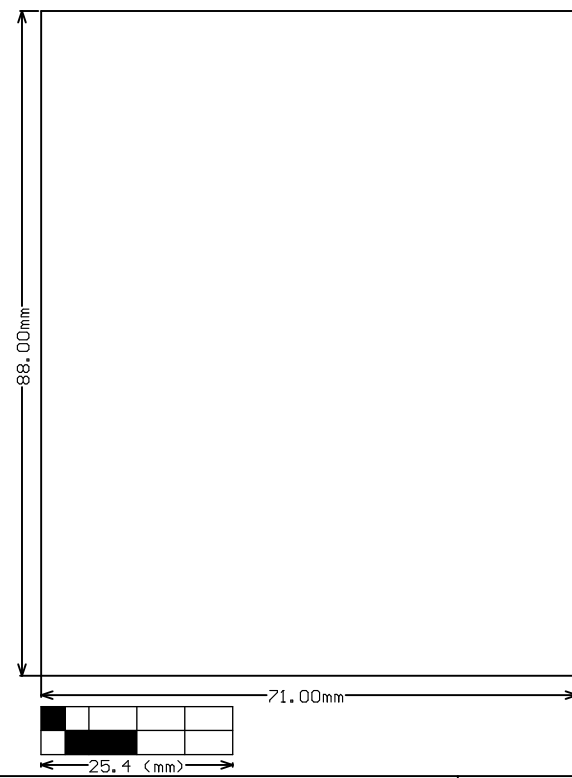
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 24.9.2015 13:30:52	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	8	0.2mm (7.874mil)	PTH	Round
○	44	0.406mm (16mil)	PTH	Round
*	98	1.016mm (40mil)	PTH	Round
×	9	1.02mm (40.157mil)	PTH	Round
⊙	2	1.1mm (43.307mil)	PTH	Round
⊠	4	3.2mm (125.984mil)	PTH	Round
165 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 24.9.2015 13:30:54	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-0503	REV: SEPIC	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 24.9.2015 13:30:56	TEXAS INSTRUMENTS	



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